Raoul Grimoldi, 13th December 2022 ERASMUS AUDITORIUM - ESTEC





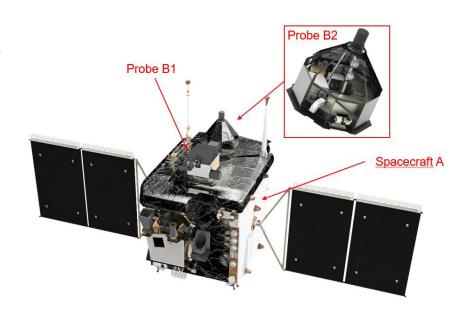
**GR740 User Day 2022** 

Hi-REL On board computer for low-cost applications



## **Comet Interceptor mission**

- Comet Interceptor is an ESA mission with payload contributions from ESA Member States and with an international participation by JAXA
- Mission selected in June 2019 as a Fast track mission in the ESA Science Programme, for a nominal launch in 2029, on a shared Ariane 6.2 flight, with the ESA mission ARIEL
- The mission will travel to an as-yet undiscovered comet, making a flyby of the chosen target when it is on the approach to Earth's orbit.
- OHB Italia has been selected as Prime Contractor for phases C/D/E1 and is also in charge of the Probe B2 Data Handling System (OBC)



Spacecraft Features:

Mass: 975kg Power: 888 W



## **Probe B2 overview**

Probe B2 includes the following equipment:

- On Board Computer (OBC), implementing both power and data handling functionalities, due to physical constrains imposed by Probe-B2 mechanical configuration, for mass/volume saving reasons
- Intersatellite Link transmitter for science data transfer to S/C A
- AOCS composed of Sun Acquisition Sensors (SAS) and Gyroscope
- Reaction wheel (RW)
- Thermal Control System (TCS) composed of heaters and thermistors
- Battery
- Three payloads
  - Entire Visible Sky (EnVisS)
  - The Optical Periscopic Imager for Comets (OPIC)
  - Dust Field & Plasma (DFP) including Flux Gate Magnetometer (FGM)



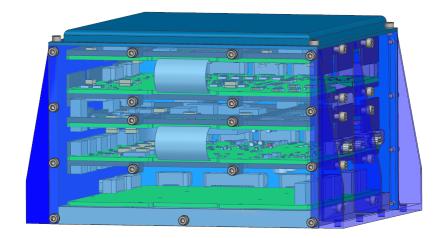


# Probe B2 OBC design main challenges

Low mass/volume

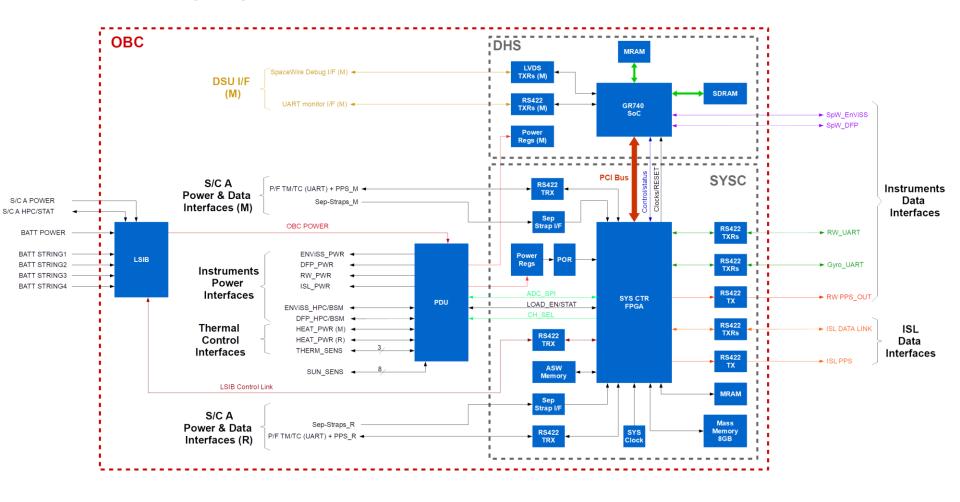
Height: 115.5 mm
Width: 200.0 mm
Depth: 164.4 mm
Mass: < 2,42 kg</li>

- Low power < 18W with full loads active</li>
- Radiation Hardening Assurance
  - TID > 10 kRad
  - SEL th > 40 MeV\*cm2/mg (Si)
  - EEE parts latch-up immune
- PCB IPC 3 + space addendum
- ECSS design flow
- Design supported by a full set of analyses





## **Probe B2 OBC architecture**





### **Probe B2 OBC architecture**

#### Data Handling System

It is in charge to manage the whole probe B2 avionics by performing the following tasks:

- AOCS
- Instruments management (HK and science data acquisition)
- Avionics subsystems management
- Probe-B2 thermal control
- Data exchange with S/C A via both umbilical link and Intersatellite link
- FDIR (both at instruments and avionics level)

#### Life Support & Interface Board (LSIB)

It is dedicated to battery management and conditioning of power provided by S/C A

#### Power Distribution Unit (PDU)

It is dedicated to distribution to payloads and avionics subsystems of power coming both from S/C A and Probe-B2 battery



## **Probe B2 OBC architecture**

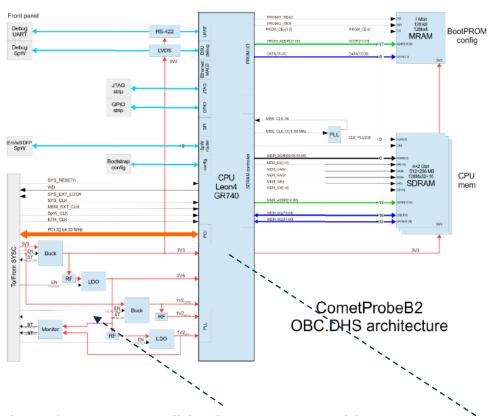
#### System Controller (SYSC)

It performs the following functions:

- DHS and PDU supervising (activation/deactivation of both DHS module and instruments, faults recovery)
- Data exchange with DHS
- On Board Time (OBT) management based on PPS signal provided by S/C A
- On board time distribution to Probe-B2 users
- Science data storage in NV mass memory
- Formatting and coding of telemetry data stream to be transmitted to the S/C A via ISL



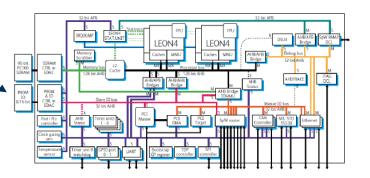
## **Probe B2 OBC architecture - DHS**



Local power conditioning composed by a set of independently controlled PoL regulators for CPU power sequencing implementation

#### Specifications:

- Boot PROM: two banks, 128kB each
- System Memory: 512MB with Reed-Solomon EDAC
- Two SpaceWire links with the instruments
- PCI local bus @ 33MHz for data exchange with the companion FPGA
- # active cores : 1
- CPU system clock frequency: 50 MHz





## **Probe B2 OBC EEE part selection**

- GR740 space plastic
- RTG4 FPGA (MIL-STD-883 Class B)
- Rad-tolerant memories
- Space Plastic Radiation Tolerant parts for analogue & power functions
- Radiation tolerant hybrid DC/DC converters in H+ quality level
- Discrete parts
  - JANTXV parts for diodes
  - ESCC qualified parts for BJT
  - Rad-tolerant MOSFETs
  - Rad-tolerant Optocouplers
- AEC-200 (Automotive) for passive parts

TID > 20 kRad

SEL immune up to 45 MeV\*cm2/mg (Si)

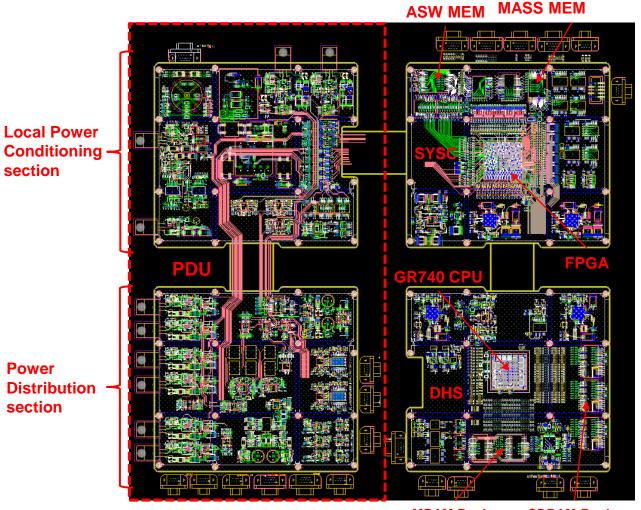


# **Probe B2 OBC layout**

section

**Power** 

section



To achieve a high level of integration, the OBC architecture PCB rigid-flex exploits the technology to minimize the box volume and mass.

The use of complex SoC like the GR740 and high-density FPGA allows to integrate all OBDH functionalities in a small volume.

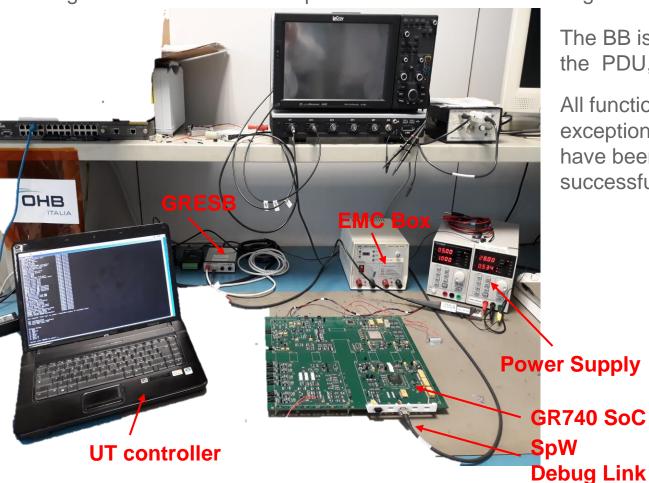
Removing the PDU power distribution section, the three rigid PCBs (DHS, SYSC and Local Power Conditioning) can be considered a very compact OBDH for small platforms

**MRAM Banks SDRAM Banks** 



# **Probe B2 OBC Elegant Breadboard**

An elegant BB has been developed for Probe-B2 as de-risking activity.



The BB is a representative model of the PDU, DHS and SYSC.

All functionalities of the OBC, with exception of battery management, have been implemented and successfully tested.



## **Probe B2 OBC Test Software**

- The Elegant BB validation test campaign has been exploited by the TCL based scripting engine provided by GRMON.
- A set of test scripts has been prepared to evaluate the correctness of the design and the hardware/software interfaces.
- A test application (TASW) has been developed. The TASW is a single task RTEMS application exploiting a console over UART to allow to execute the test functionalities.
- The RTEMS used to produce the executable is the RTEMS QDP by ESA.

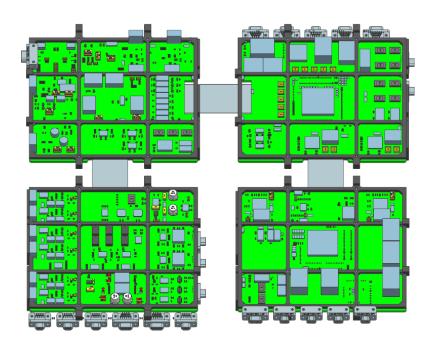
```
🔥 lcavalli@sde-ref-01:~/Progetti, 🗙
  * MATN MENU **
      Memory test
OBT test
      S/C TM/TC interface test
      GYRO interface test
       Reaction Wheel interface test
      ISL interface test
 Select menu entry: 3
  * ON-BOARD TIME MENU **
      obt_GetOBTError
obt_GetPPSValid
      obt_SetPPSValid
      obt_UpdateOBT
       On-Board Time status
Select menu entry: 1
Microseconds: 216407
  NFO]: Result: 0x07000000
  * ON-BOARD TIME MENU **
      obt_GetOBTError
obt_GetPPSValid
      obt_SetPPSValid
obt_UpdateOBT
       On-Board Time status
Select menu entry: 7
OBT_CMD:
                   freeze:
                             0×0
OBT_PPS_VALUE:
                              0×000000
                   value:
OBT CORRECTION: enabled:
OBT_CORRECTION:
                  command
OBT_CORRECTION:
                   interval
OBT_CORRECTION
                              0x00000
OBT ERROR:
                              0x000000
 DBT_SEC_PRESET:
                 preset
OBT_US_FREEZED:
                              0x034D57
OBT SEC FREEZED: sec:
                              0×000000022
```

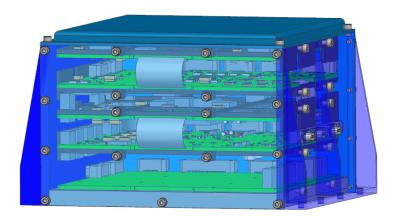


# **Probe B2 OBC Development**

The following models are foreseen

- EQM model with Rigi-flex PCB to be housed in a representative mechanical design by end of 2023
- PFM Model delivered by August 2024.



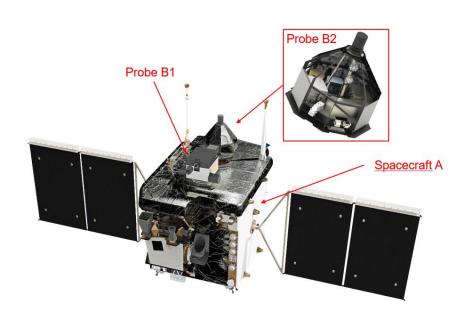




## Probe B2 OBC in OHB - Italia OBC Roadmap

- GR740 SoC has been selected for the OHB-I new generation OBC architecture being available on the market on both Space Plastic and Class 1 quality level
- The designed architecture can be applied for
- High Rel Space Computer for mainstream missions adopting Class 1 parts with more standard form factor (e.g. Space VPX or cPCI Serial)
- "New Space" missions where RHA and well proved reliability is required
- The architecture is scalable in term of
- Computational power/Power consumption
- EEE part quality level / cost
- Probe B2 OBC represent the first implementation of the "New Space" version, fully customized with additional functions required for Comet-Interceptor mission





# Thank You for your attention!

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